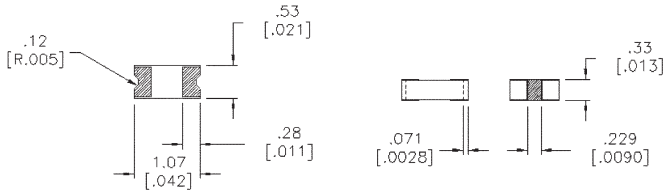
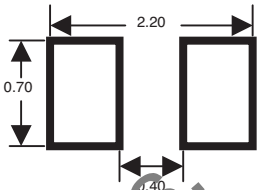
Product Dimensions: mm [inches]



Solder Pad Recommendation: mm [inches]



Design Considerations

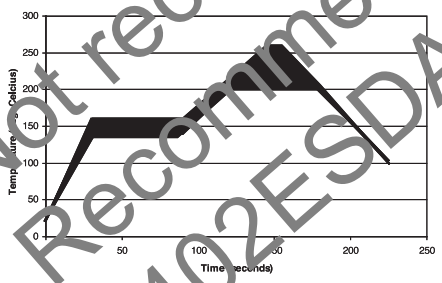
The location in the circuit for the MLP family has to be carefully determined. For better performance, the device should be placed as close to the signal input as possible and ahead of any other component. Due to the high current associated with an ESD event, it is recommended to use a “0-stub” pad design (pad directly on the signal/data line and second pad directly on common ground).

Environmental Specifications:

- Load Humidity: 12VDC per EIA/IS-772 Para. 4.4.2, +85°C, 85% RH for 1000 hours
- Thermal Shock: EIA/IS-722 Para 4.6, Air to Air -55°C to +125°C, 5 cycles
- Moisture Resistance Test: MIL-STD-202G Method 106G, 10 cycles
- Mechanical Shock: EIA/IS-722 Para. 4.9
- Vibration: EIA/IS-722 Para. 4.10
- Resistance to Solvent: EIA/IS-722 Para. 4.11
- Operating & Storage Temperature Range: -55°C to +125°C

Soldering Recommendations

- Compatible with lead and lead-free solder reflow processes
- Peak reflow temperatures and durations:
  - IR Reflow = 260°C max. for 10 sec. max.
  - Wave Solder = 260°C max. for 10 sec. max.
- Recommended IR Reflow Profile:



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